Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

QT-Brightek Optocoupler Series

4-PIN DC Input Photodarlington

Part No.: QTM415

Table of Contents:

Introduction

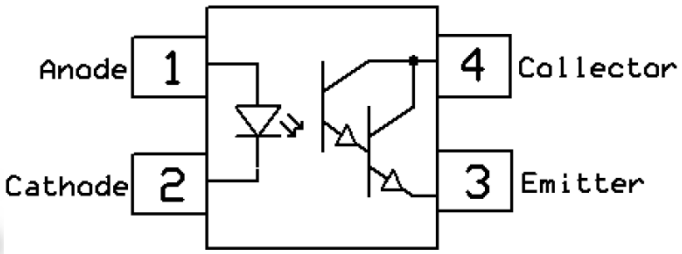
Feature:

- High Isolation voltage between input and output (Viso = 3750V rms)
- DC input with transistor output
- Operating Temperature up to 110 ºC
- Mini-Flat package

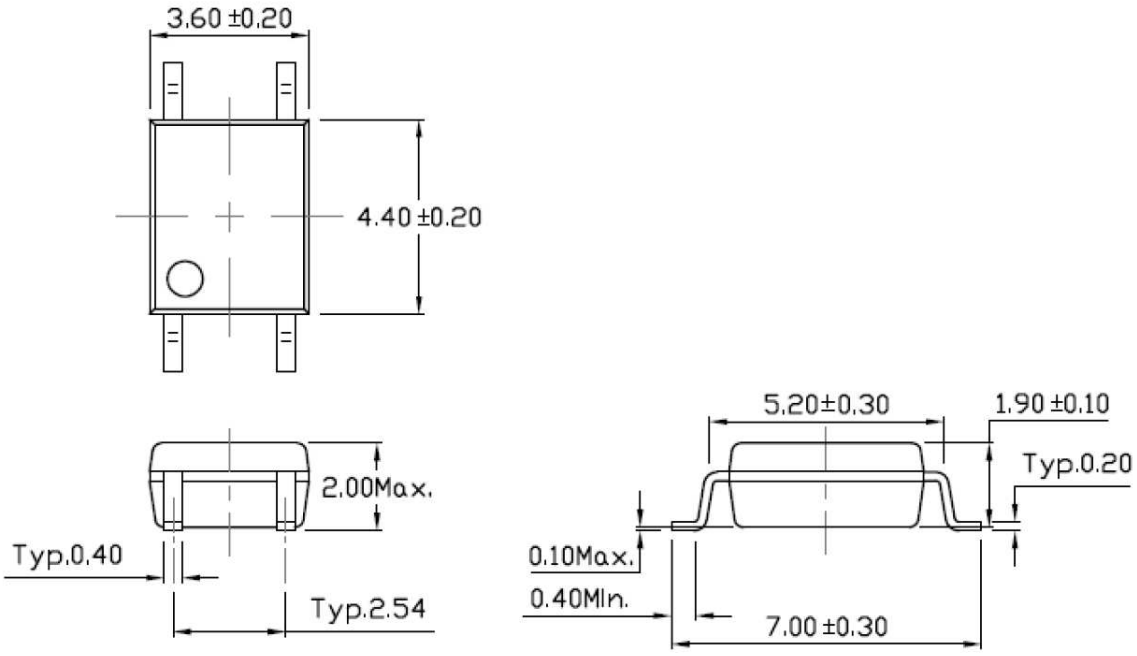
Certification & Compliance:

- Pb free and RoHS Compliant
- UL recognized (File #E338132)
- cUL recognized (File #E338132)
- VDE (Pending Approval)

Schematic:



Dimension: (Dot location indicates pin 1)



- All Dimensions are in mm

Absolute Maximum Rating

Symbol	Parameter	Rating	Units
V_{ISO}	Isolation Voltage	3750	V_{RMS}
T_{STG}	Storage Temperature	-55 ~ +150	ºC
T_{OPR}	Operating Temperature	-55 ~ +110	ºC
T_{SOL}	Lead Solder Temperature	260 for 10 sec	ºC
P_{TOT}	Total Power Dissipation	170	mW
EMITTER			
I_F	Continuous Forward Current	50	mA
I_{FP}	Peak Forward Current (≤ 1us, 300pps)	1	A
V_R	Reverse Voltage	6	V
P_D	Power Dissipation	70	mW
	Power Dissipation Derated above 100ºC	-	mW/ºC
DETECTOR			
B_{VCEO}	Collector-Emitter Breakdown Voltage	60	V
B_{VECO}	Emitter-Collector Breakdown Voltage	7	V
I_C	Collector current	80	mA
P_C	Power Dissipation	150	mW

Electrical Characteristic (T_A=25 °C)

Emitter

Symbol	Characteristics	Device	Test Condition	Range			Unit
				Min	Typ	Max	
V_F	Forward Voltage	-	I_F = 10mA	-	1.4	1.6	V
I_R	Reverse Current		V_R=6V	-	-	5	uA
C_{IN}	Input Capacitance		f =1kHz	-	10	250	pF

Detector

Symbol	Characteristic	Device	Test Condition	Range			Unit
				Min	Typ	Max	
B_{VCEO}	Collector-Emitter Breakdown Voltage	-	I_C=100uA	35	-	-	V
B_{VECO}	Emitter-Collector Breakdown Voltage	-	I_C=100uA	7	-	-	uA
I_{CEO}	Collector-Emitter Dark Current	-	V_{CE}=10V, I_F=0mA	-	-	1	uA

Transfer Characteristics (T_A=0 to 70C unless specified otherwise)

Symbol	Characteristic	Device	Test Condition	Range			Unit
				Min	Typ	Max	
CTR	Current Transfer Ratio	QTM415	I_F = 1mA, V_{CE}=2V	600	-	-	%
		QTM415A		3000	-	6500	
		QTM415B		5500	-	-	
$V_{CE(SAT)}$	Collector-Emitter Saturation Voltage		I_F = 20mA, I_C=5mA	-	0.8	1	V
R_{IO}	Isolation Resistance		V_{IO}=500V_{DC}	$5x10^{10}$	-	-	Ω
C_{IO}	Isolation Capacitance		f=1MHz	-	0.5	1.0	pF

Switching Characteristics (TA=25°C, Vcc=5V)

Symbol	Characteristic	Device	Test Condition	Range			Unit
				Min	Typ	Max	
t_r	Rise Time		I_C=2mA, V_{CE}2V, R_L=100Ω	-	-	300	us
t_f	Fall Time			-	-	250	

Characteristic Curves

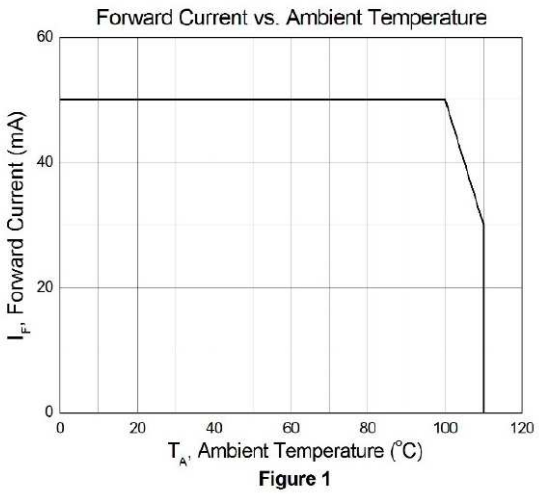


Figure 1

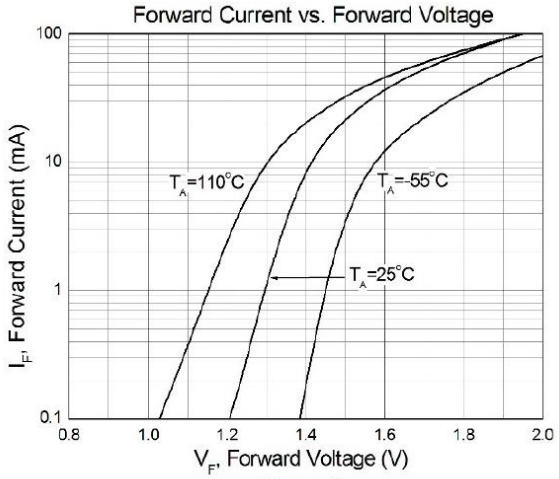


Figure 2

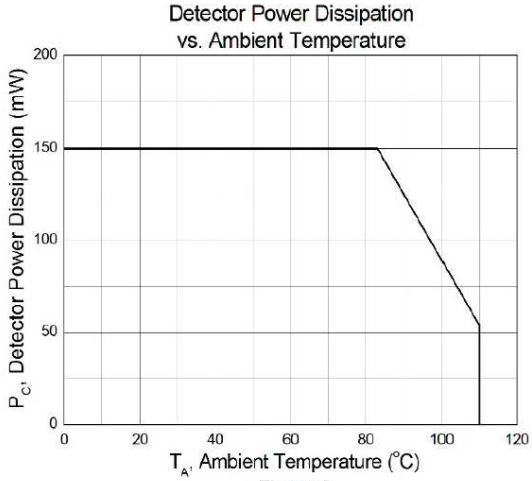


Figure 3

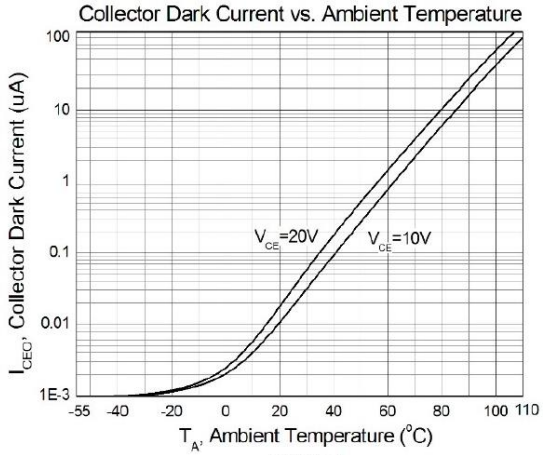


Figure 4

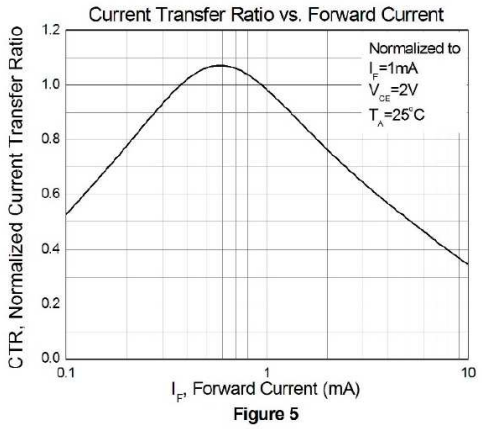


Figure 5

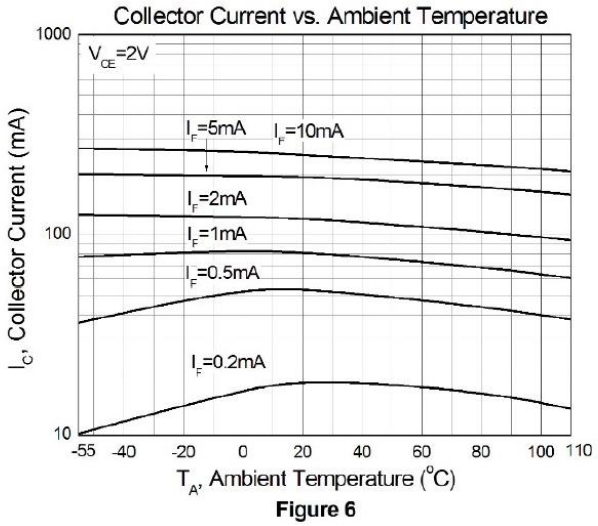


Figure 6

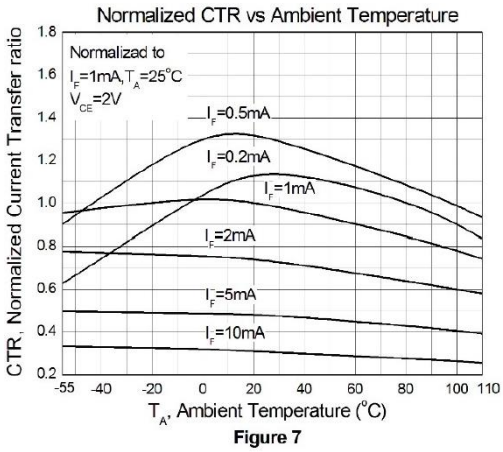


Figure 7

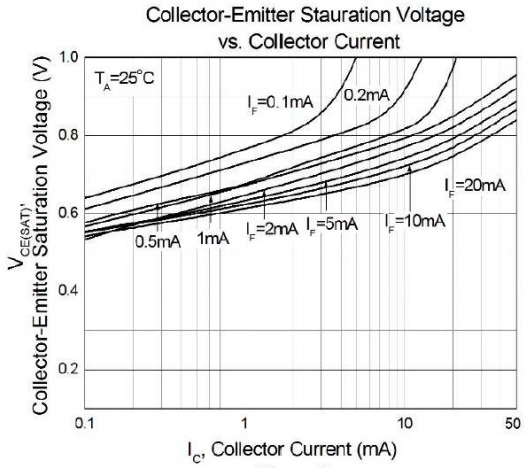


Figure 8

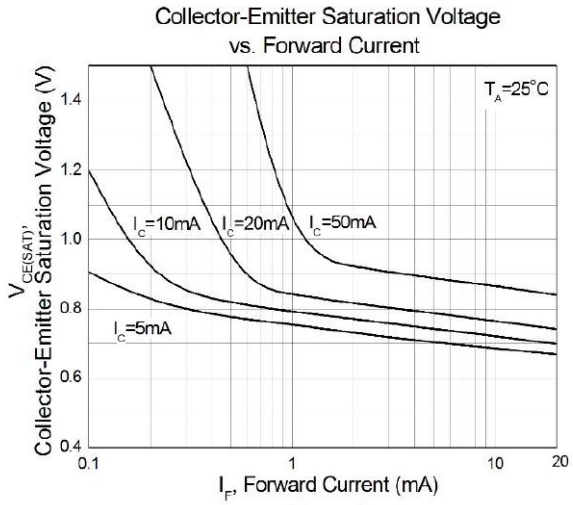


Figure 9

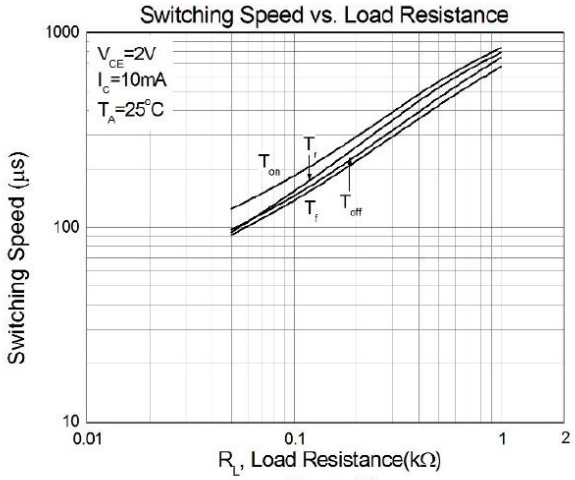


Figure 10

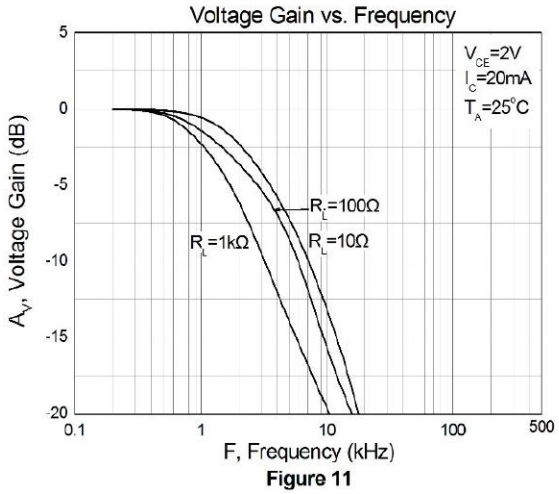


Figure 11

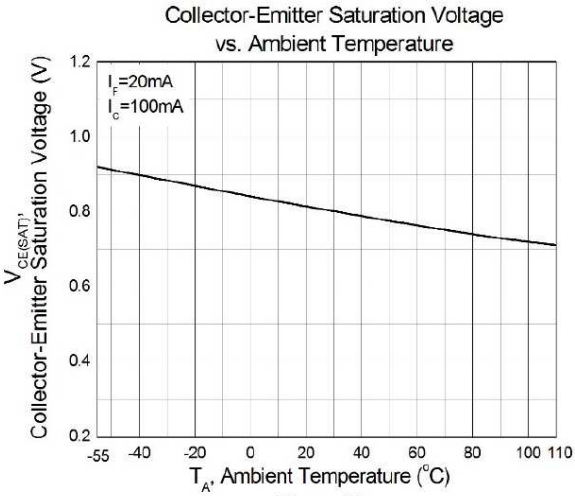
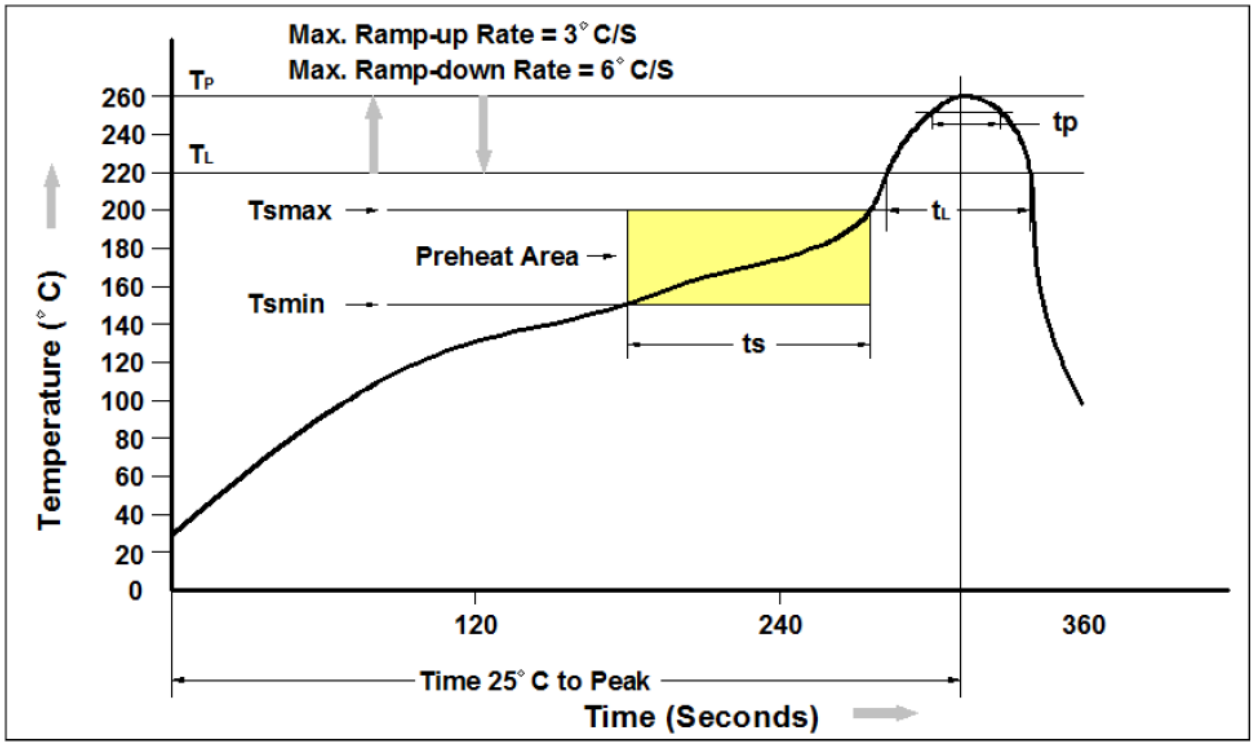
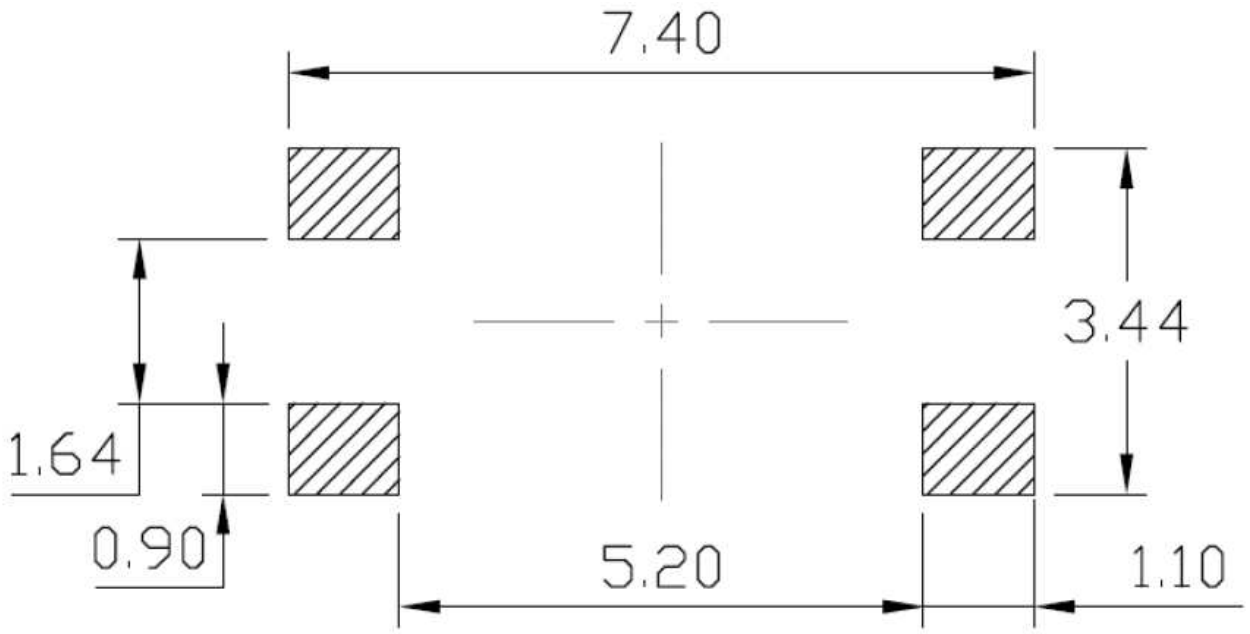


Figure 12

Solder Profile & Footprint



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150℃
Temperature Max. (Tsmax)	200℃
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t_L to t_P)	3℃/second max.
Liquidous Temperature (T_L)	217℃
Time (t_L) Maintained Above (T_L)	60 – 150 seconds
Peak Body Package Temperature	260℃ +0℃ / -5℃
Time (t_P) within 5℃ of 260℃	30 seconds
Ramp-down Rate (T_P to T_L)	6℃/second max
Time 25℃ to Peak Temperature	8 minutes max.



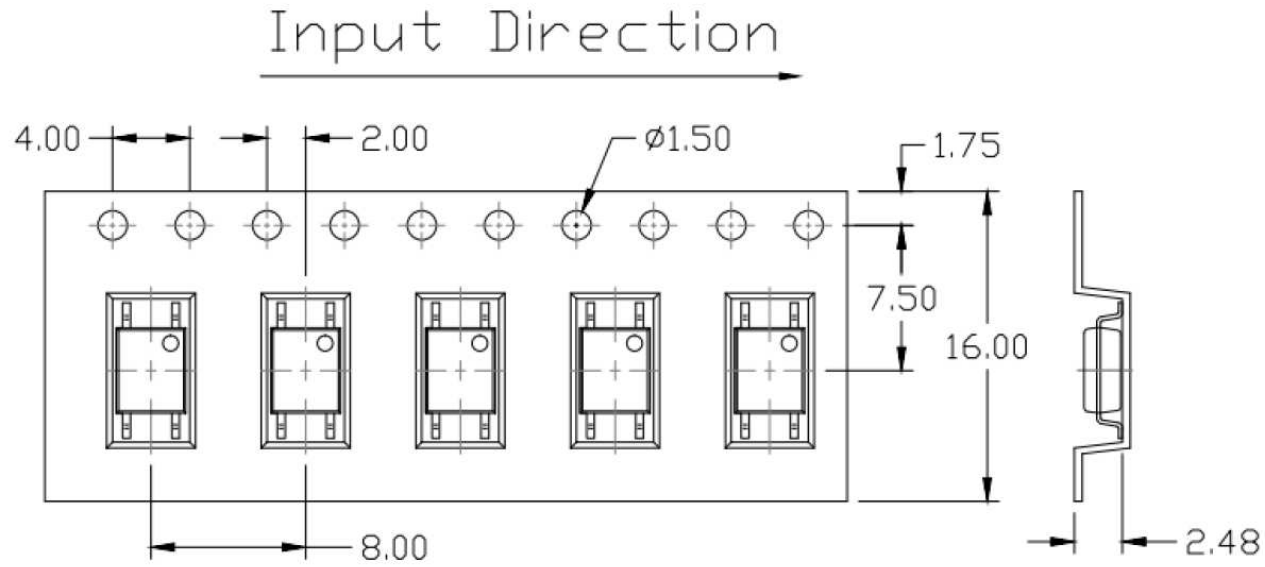
Recommended Solder Footprint for SMD Leadform

Units: mm tolerance: +/- 0.1mm

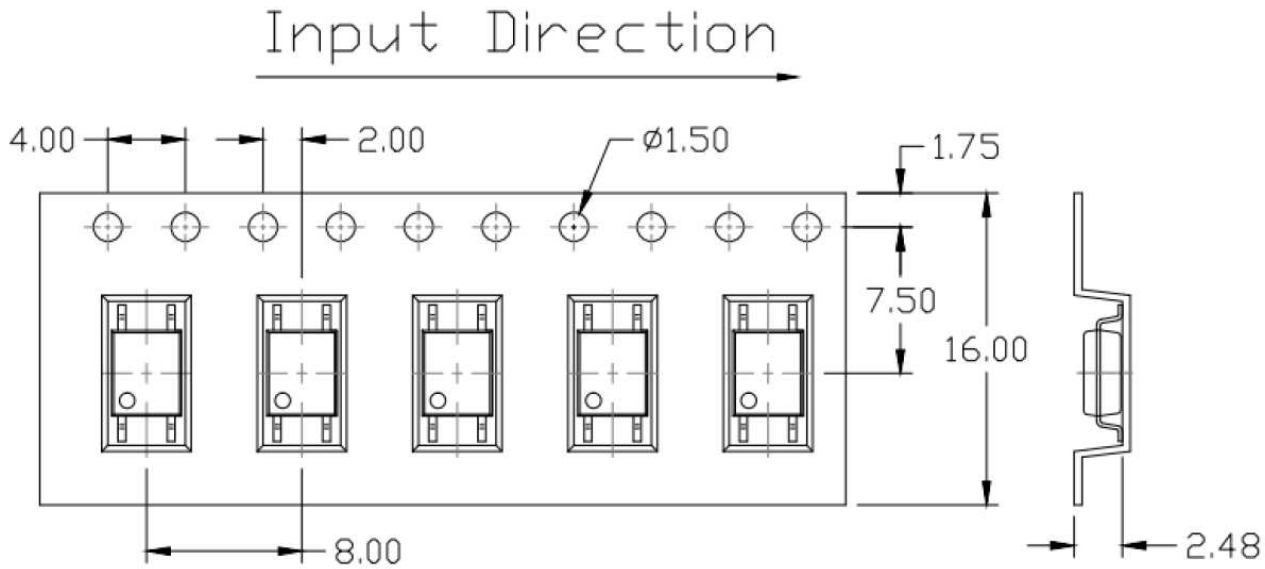
Packing & Labeling

Tape Dimension:

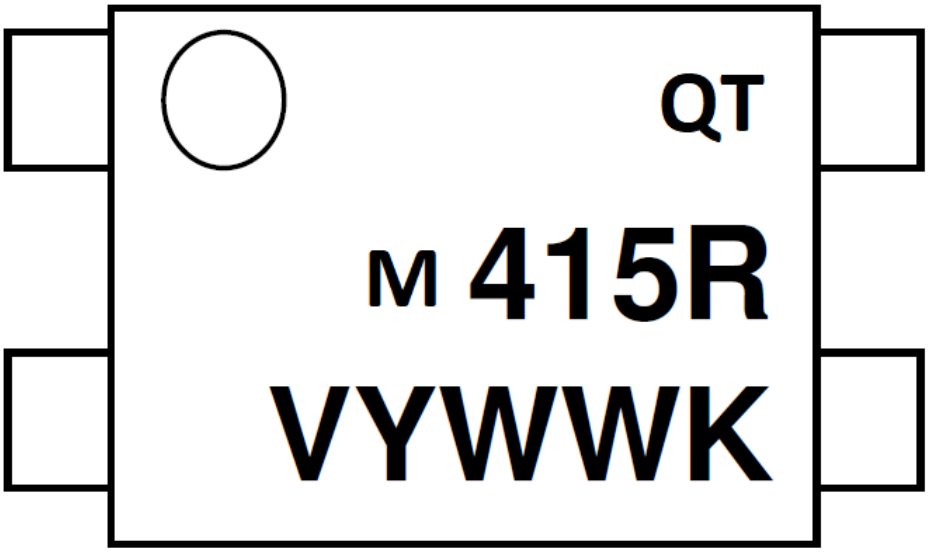
Option (T1)



Option (T2)



Device Marking



QT = QT-Brightek Corporation
M= Mini-Flat Package
415 = part number
R= CTR Rank
Y = Year
WW = Week
V = VDE Option
K= Manufacturing code

Ordering Information

QTM415X(V)(Z)
X = Part number (X=A,B or None)
V = VDE option (V or None)
Z = Tape and reel option (T1 or T2)

Option	Description	Quantity
T1	Surface Mount Lead Forming – with Option 1 Taping	3000 pcs/ reel
T2	Surface Mount Lead Forming – with Option 2 Taping	3000 pcs/ reel

Revision History

Description:	Revision #	Revision Date
Initial release of QTM415	1.0	02/08/2018
Amend the Marking	1.1	04/13/2018

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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.